

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9136xxxxDR-G
Typical Mass: 12 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.259	Silicon	104900	7440-21-3
	-	Arsenic	6	7440-38-2
Lead pad	2.831	Nickel	236000	7440-02-0
	0.223	Silver	18600	7440-22-4
	0.042	Gold	3500	7440-57-5
Die attach	0.042	Epoxy Resin	3500	—
	0.036	Silica	3000	60676-86-0
Bonding wire	0.371	Gold	30900	7440-57-5
Resin	6.476	Silica	539700	60676-86-0
	0.396	Epoxy Resin	33000	—
	0.324	Phenol Resin	27000	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."